



Description

The HXY2101EI uses advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as a load switch or in PWM applications.

General Features

$V_{DS} = -20V, I_D = -1.8A$

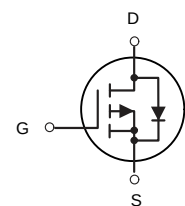
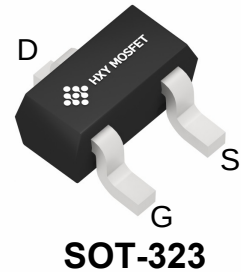
$R_{DS(ON)} < 150m\Omega @ V_{GS} = -4.5V$

Application

Battery protection

Load switch

Uninterruptible power supply



P-Channel MOSFET

Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HXY2101EI	SOT-323	TS1	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 8	V
I_D	Drain Current-Continuous	-1.8	A
I_{DM}	Drain Current-Pulsed (Note 1)	-3	A
P_D	Maximum Power Dissipation	0.29	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 2)	431	°C/W



Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

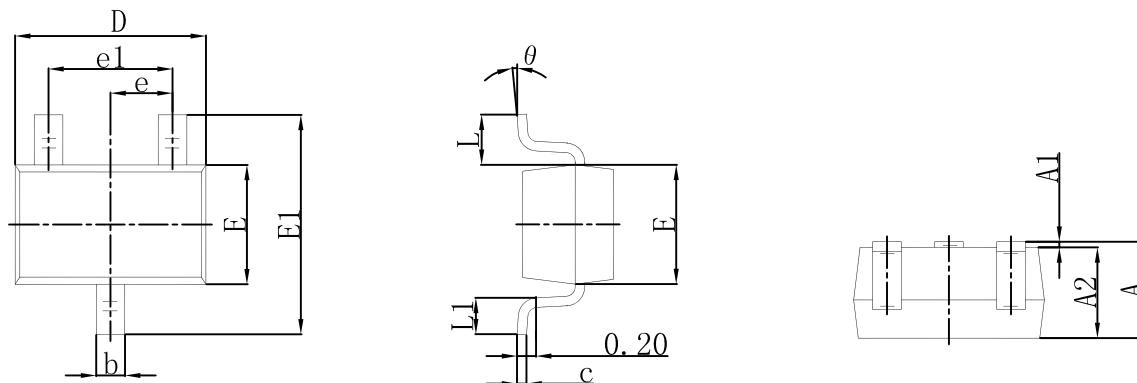
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
STATIC CHARACTERISTIC						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =-250μA	-20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-18V,V _{GS} = 0V			-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±12V, V _{DS} = 0V			±100	nA
Gate threshold voltage (note2)	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.4	-0.7	-1.0	V
Drain-source on-resistance (note2)	R _{DS(on)}	V _{GS} =-4.5V, I _D =-2A			150	mΩ
		V _{GS} =-2.5V, I _D =-1.0A			230	mΩ
Maximum Continuous Drain to Source Diode Forward Current	I _S	--			-1.0	A
Diode forward voltage	V _{SD}	I _S =-1.0A, V _{GS} =0V			-1.2	V
DYNAMIC CHARACTERISTICS (note3)						
Input capacitance	C _{iss}	V _{DS} =-8V,V _{GS} =0V, f =1MHz			680	pF
Output capacitance	C _{oss}				130	pF
Reverse transfer capacitance	C _{rss}				95	pF
SWITCHING CHARACTERISTICS (note3)						
Turn-on delay time	t _{d(on)}	V _{GS} =-4.5V,V _{DS} =-10V, I _D =-1.0A,R _G =5.1Ω			10	nS
Turn-on rise time	t _r				20	nS
Turn-off delay time	t _{d(off)}				35	nS
Turn-off fall time	t _f				18	nS

Notes:

1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse Width=300 μs , Duty Cycle=2%.
3. These parameters have no way to verify.



SOT-323 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
K	0°	8°	0°	8°



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